

Topic	<i>P is a Paper, R is a Review</i>	Type	Author Firstname	Author Surname	Reviewer Firstname	Reviewer Surname	Vol / No	Page
3D Interconnect		R	Ollie	Althorpe	Martin	Goosey	5/3	07
3D Lithography		R	Gavin	Williams	Martin	Goosey	5/3	10
3D Packaging		R	Andrew	Richardson	Martin	Goosey	5/3	06
3D Technology Developments		R	Prof.Martin	Goosey	Martin	Goosey	5/3	07
ASPIS project P7		R	Martin	Goosey	Martin	Goosey	5/4	09
ASPIS-12 months of progress-1/1/2012		P	Prof.Martin	Goosey			5/1	10-15
ASPIS-update on EU P7 and Susonence-12/6/12		R	Pete	Starkey	Pete	Starkey	5/4	05
Adhesive flip chip assembly		R	Andrew	Holmes	Martin	Goosey	5/3	09
Artificial Optical Radiation Directive		P	Len	Pillinger			1/3	03-4
Be British, Think Global		R	Steve	Driver	Pete	Starkey	5/4	11
Blind Via Holes		P	Bob	Willis			1/1	08-10
Boundary Scan Testing		R	Karl	Miles	Pete	Starkey	1/1	04
CMOS - Integrated Micro & Nano Systems		R	Stewart	Smith	Martin	Goosey	5/3	10
Capability approvals		R	Len	Pillinger	Pete	Starkey	1/1	05
Cleaning contacts - mechanisms and benefits		R	Mike	Partridge	Pete	Starkey	5/1	16
Copper filled conductive adhesives		R	David	Hutt	Martin	Goosey	5/3	09
DNA as a Digital Storage Medium		P	Prof.Martin	Goosey			5/4	03
Defect - Industry Database		R	Dr Chris	Hunt	Pete	Starkey	1/1	04
Defect Database		P	Bob	Willis			1/1	03
Design for manufacture		R	Matthew	Beadel	Martin	Goosey	1/2	08
Digital Tools for DIX		R	Stoyan	Stoyanov	Martin	Goosey	5/3	10
ECDs - Multilayer Electroceramic Devices		R	Dr Bala	Vaihyant	Martin	Goosey	5/3	11
EDA tools		R	Per	Viklund	Martin	Goosey	5/3	06
EPIC electrometer		R	Keith	Strickland	Martin	Goosey	5/3	07
EU-funded projects		R	Prof.Martin	Goosey	Pete	Starkey	5/1	16
Electrical contact interfaces		R	Liudi	Jiang	Martin	Goosey	5/3	08-9
Electroless Coper - Ultrasound effects		R	Dr.Andy	Cobley	Pete	Starkey	5/1	16-17
Electroless Nickel - Emmersion Gold-Finishes		R	Prof.Martin	Goosey	Pete	Starkey	5/2	04
Electroless Nickel - Emmersion Gold-Supplier		R	Nigel	White	Pete	Starkey	5/2	03
Electroless Nickel - Emmersion Gold-User		R	Dennis	Price	Pete	Starkey	5/2	03-4
Electroless copper plating & effect of ultrasound		R	Amirah	Kassim	Pete	Starkey	5/4	17
Electropolishing of aerospace alloys		R	Karl	Ryder	Martin	Goosey	5/4	10
Embedded RFID's		R	Alex	Bindel	Martin	Goosey	5/3	08
Energy Storage		R	Christian	Klumpner	Martin	Goosey	5/3	09
Energy efficiency - 'path to'		R	Stuart	Dalrymple	Martin	Goosey	5/4	08
Energy generation and storage on textiles		R	David	Harrison	Martin	Goosey	5/3	10
Fab3D - nanoparticulate layers		R	Yiannis	Vardaxogl	Martin	Goosey	5/3	09
Fine-line imaging automated process line		R	Lawson	Lighthfoot	Pete	Starkey	5/4	05-06
Flip-chip solder joints - non-destructive monitoring		R	Ryan	Swee How	Pete	Starkey	5/4	16
Functional Oxides Development		R	Derek	Sinclair	Martin	Goosey	5/3	11
Functionalisation of metallic nanoparticles.		R	John	Graves	Martin	Goosey	5/3	09
Graphene-Potential Interconnect Applications		P	Prof.Martin	Goosey			5/2	5-8
HESLIS - transparent conductors		R	Yiannis	Vardaxogl	Martin	Goosey	5/3	09
HF flexible fabric electronics		R	Yiannis	Vardaxogl	Martin	Goosey	5/3	09
High Speed electronics and optoelectronics		R	Jeremy	Everard	Martin	Goosey	5/3	09
High Value Manufacturing Centre		R	Alan	McClellanc	Martin	Goosey	5/3	10
High-speed PCB materials - characteristics		R	Alun	Morgan	Pete	Starkey	5/4	16-17
Human development		R	Nigel	Risner	Pete	Starkey	5/4	12-13
IPC 2011 Technology Roadmap		P	Len	Pillinger			5/3	03-5
Immersion gold processes - deep-eutectic solvents		R	Dr. Karl	Ryder	Pete	Starkey	5/4	17-18
Impedance - controlled		R	Neil	Chamberlc	Martin	Goosey	1/2	07
Integrating Electronics		R	Chris	Rider	Martin	Goosey	5/3	06
Interconnect Opt. & Elect.		P	Hadi	Bagshiahi			1/3	09-12
Interconnect Opt. & Elect.		P	John	Chappell			1/3	09-12
Interconnect Opt. & Elect.		P	Paul P	Conway			1/3	09-12

Topic	<i>P is a Paper, R is a Review</i>	Type	Author Firstname	Author Surname	Reviewer Firstname	Reviewer Surname	Vol / No	Page
Interconnect Opt. & Elect.	P	P	F. Anibal	Fernández			1/3	09-12
Interconnect Opt. & Elect.	P	P	David A	Hutt			1/3	09-12
Interconnect Opt. & Elect.	P	P	Aongus	McCarthy			1/3	09-12
Interconnect Opt. & Elect.	P	P	Dave	Milward			1/3	09-12
Interconnect Opt. & Elect.	P	P	Ioannis	Papakonsta			1/3	09-12
Interconnect Opt. & Elect.	P	P	David R	Selviah			1/3	09-12
Interconnect Opt. & Elect.	P	P	Himanshu	Suyal			1/3	09-12
Interconnect Opt. & Elect.	P	P	Andy C	Walker			1/3	09-12
Interconnect Opt. & Elect.	P	P	Kai	Wang			1/3	09-12
Interconnect Opt. & Elect.	P	P	Agnieszka	Wozna			1/3	08
Interconnect Opt. & Elect.	P	P	Shefiu S	Zakariyah			1/3	09-12
Interconnection - Trends	R	R	Prof. Martin	Goosey	Pete	Starkey	1/1	04
Interconnects - ultra-fine pitch	R	R	Changqing	Liu	Pete	Starkey	5/4	15-16
Ionic liquid electrolytes in surface finishing processes	R	R	Karl	Ryder	Martin	Goosey	5/4	07
L(leMRC)- Innovative Electronics Manufacturing Rsearch Centre	R	R	Dr.Darren	Cadman	Pete	Starkey	5/2	09
Laminates - unreinforced thermoplastic	R	R	Martin	Wickham	Pete	Starkey	1/1	05
Laser direct writing	R	R	David	Watson	Martin	Goosey	5/3	09
Lead-Free soldering	R	R	Bob	Willis	Pete	Starkey	1/1	05
Lean and Benchmarking - a driver for growth	R	R	Mark	Knowlton	Pete	Starkey	5/4	06
Liquid crystal on silicon micro- displays	R	R	Stewart	Smith	Martin	Goosey	5/3	10
Loss bundle	R	R	Martyn	Gaudion	Pete	Starkey	1/1	04
MEA-Biochip with Micro-well Features	P	P	Paul	Conway			5/1	05-9
MEA-Biochip with Micro-well Features	P	P	Xiaoyun	Cui			5/1	05-9
MEA-Biochip with Micro-well Features	P	P	Chris	Denning			5/1	05-9
MEA-Biochip with Micro-well Features	P	P	Olivia	Flaherty			5/1	05-9
MEA-Biochip with Micro-well Features	P	P	David	Hutt			5/1	05-9
MEA-Biochip with Micro-well Features	P	P	DivYa	Rajamohar			5/1	05-9
MEA-Biochip with Micro-well Features	P	P	Andrew	West			5/1	05-9
Magnetic Components	R	R	Stewart	Smith	Martin	Goosey	5/3	10
Material innovations for power electronics equipment	R	R	Manfred	Walchshofe	Pete	Starkey	5/4	05
Medical Devices and Artificial Muscles.	R	R	Philip	Breedon	Martin	Goosey	5/3	10
Medical Electronics Packaging	R	R	Dr Anne	Vanhoest	Martin	Goosey	5/3	10
Microelectronic interconnects	R	R	Maria	Mirdkizoudi	Martin	Goosey	5/3	09
NPL Industry Defect Database	P	P	Bob	Willis			1/1	03
Nanocoat Aluminium anodisation techniques.	R	R	David	Hall	Martin	Goosey	5/4	09-10
Nanomachining CNC tool	R	R	Tony	Corless	Martin	Goosey	5/3	09
Nickel recovery - 'new technologies' (1st Project)	R	R	Rod	Kellner	Martin	Goosey	5/4	08
Nickel recovery - 'new technologies' (2nd Project)	R	R	Paul	Fitzpatrick	Martin	Goosey	5/4	09
PCB Costing	P	P	David	Kingsley			1/2	12-17
PCB Design	P	P	Sue	Critchler			1/3	05-6
PCB Greener Production	P	P	Prof. Martin	Goosey			1/1	06-7
PCB design - Typical errors	R	R	Sue	Critchler	Martin	Goosey	1/2	07
PCB failure analysis techniques	R	R	Dr Chris	Hunt	Pete	Starkey	5/2	04
PCB manufacture - Flex-rigid trends	R	R	Dennis	Price	Pete	Starkey	1/1	04
Packet switching	R	R	Rehana	Kausar	Martin	Goosey	5/3	09
Photonic processing	R	R	Wayne	Crayton	Martin	Goosey	5/3	09
Power modules - high-performance low-cost	R	R	Prof.Mark	Johnson	Pete	Starkey	5/4	15
Printed Electronics	R	R	Darren	Southee	Martin	Goosey	5/3	11
Printing, coating and nano-imprinting equipment	R	R	Thomas	Kolbusch	Pete	Starkey	5/4	06
Product Lifecycle Management	R	R	Jan	Keijzer	Martin	Goosey	1/2	07
Pyroelectric materials, and their applications.	R	R	Prof.Roger	Whatmore	Pete	Starkey	5/4	14
REACH - EU Legislation	R	R	Mike	Inman	Pete	Starkey	1/1	05
REACH - Enforcement & Registration	P	P	Len	Pillinger			1/2	05
REACH - Exemptions	P	P	Len	Pillinger			1/2	05
REACH - Impact on the supply chain	P	P	Len	Pillinger			1/2	05
REACH - What exactly is it ?	P	P	Len	Pillinger			1/2	03-6

Topic	<i>P is a Paper, R is a Review</i>	Type	Author Firstname	Author Surname	Reviewer Firstname	Reviewer Surname	Vol / No	Page
REACH Regulation		P	Len	Pillinger			1/3	03-4
REACH is 'No Data - No Market'		P	Len	Pillinger			1/2	04
Registration controlling in PCB manufacture		R	Dominic	Millett	Pete	Starkey	5/4	12
Research Project from Initiation to Industrialisation		R	Martin	Goosey	Martin	Goosey	5/3	10
RoHS-46 New Materials		P	Len	Pillinger			1/3	03-4
Screen printing of Carbon Nanotubes		R	Wenhui	Song	Martin	Goosey	5/3	11
Self-repairing electronics related mechanisms		R	Richard	McWilliam	Martin	Goosey	5/3	10-11
Sell the Advantage, Not the Commodity		R	Bill	Burr	Pete	Starkey	5/4	04
Skin effect - loss		R	Martyn	Gaudion	Pete	Starkey	1/1	04
Solar Powered Hydrogen Generation.		R	Rhys	Rhodes	Martin	Goosey	5/3	10
Solder materials for use up to 185 C		R	Samjid	Mannan	Martin	Goosey	5/3	11
Solderability Finish Faults		R	Bob	Willis	Pete	Starkey	5/2	03
Sonochemical Techniques		P	Dr Andy	Cobley			1/2	09-11
Supply Procedures for Military Contracts 1st.Pt		R	Paul	Green	Pete	Starkey	5/4	14
Supply Procedures for Military Contracts 2nd.Pt		R	Dr.Linda	Newnes	Pete	Starkey	5/4	15
Susonence		P	Prof.Martin	Goosey			5/1	03-4
Susonence		R	Dr.Andy	Cobley	Martin	Goosey	5/4	07-08
Thermally conductive dielectric coating		R	Dr Pavel	Shaskov	Pete	Starkey	5/4	12
Tin whiskers		P	Kurt	Jacobsen			1/3	07-8
Tin whiskers		P	George	Milad			5/3	12-16
Tin whiskers		P	Professor Bill	Plumridge			1/3	08
Tin whiskers		R	Geoff	Wilcox	Martin	Goosey	5/3	11
Traceability - use of RFID tags		R	Axel	Bindel	Pete	Starkey	5/4	17
ULTIEmet project - electroless metallisation		R	Dr.Andy	Cobley	Martin	Goosey	5/4	10
Vacuum Web Coating		R	Hazel	Assender	Martin	Goosey	5/3	08
Via-hole plugging techniques		R	Bob	MacRae	Pete	Starkey	5/4	04
White Solder Mask Inks		R	Geoff	Layhe	Pete	Starkey	5/1	10
Wire-bond reliability under extreme environments		R	Maria	Mergkizouc	Pete	Starkey	5/4	16